



Datasheet – MSI2006

6A Bi-directional Load Switch for Tablet

General Description

The MSI2006 is a low Ron P-channel MOSFET controlled by a soft-start sequence of 2ms for Mobile applications.

Bi-directional switching allows reverse current from V_{OUT} to V_{IN} . The switching is controlled by active-LOW logic input the ENB pin.

The input voltage range operates from 2.3V to 5.5VDC to support a wide range of applications in consumer, optical, storage, portable and industrial device power management.

The device is packaged 1.235mm x 1.625mm, Wafer-Level Chip-Scale Package (WLCSP).

Features

- Wide Input Voltage : 2.3V to 5.5V
- Low $R_{DS(ON)}$: 7 mΩ (Typ.)
- Slew Rate/Inrush Control : 2.0ms(Typ.)
- 6A Maximum Continuous Current
- Low Off Switch Current : < 1uA
- Reverse Current Blocking (RCB) during OFF
- ESD Protected
 - Human Body Model : > 8.0kV
 - Charged Device Model : > 2.0kV

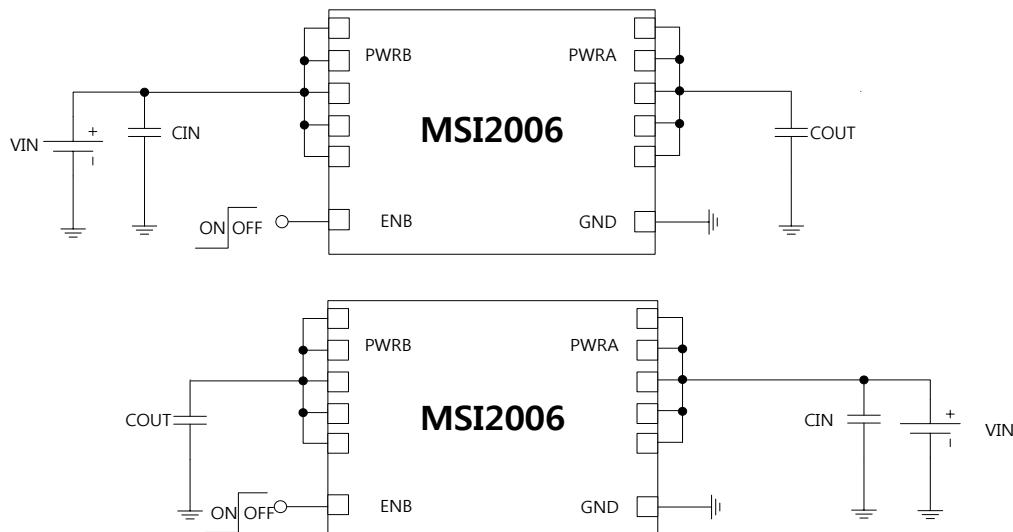
Applications

- Tablet
- Storage, DSLR, portable Devices

Ordering Information

| Part Number | Top Marking | Ambient Temperature Range | Package | RoHS Status |
|-------------|-------------|---------------------------|----------------------------------|-------------------------|
| MSI2006WCRH | M06 | -40°C to +85 °C | 1.235 mm X 1.625 mm WLCSP-12Ball | Halogen Free Pb-Free |

Typical Application





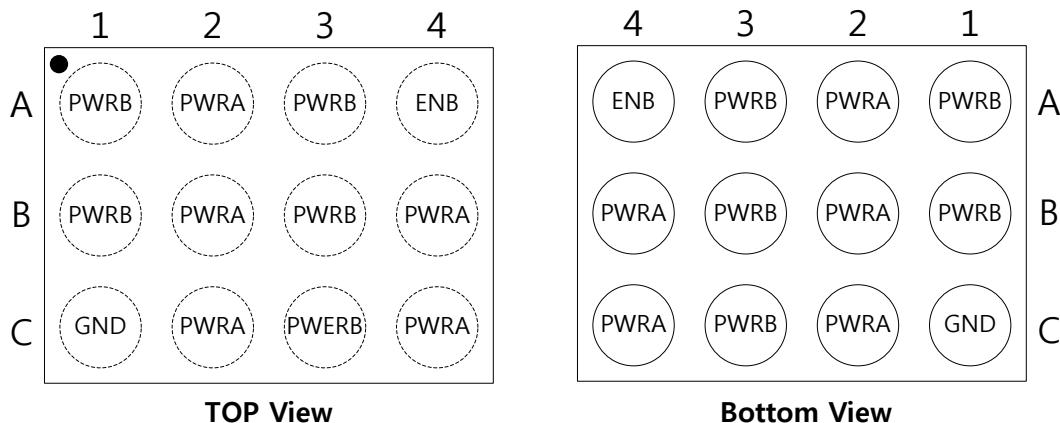
RoHS Compliant
HALOGEN-FREE

Confidential

Datasheet Version 1.0

Pin Configuration

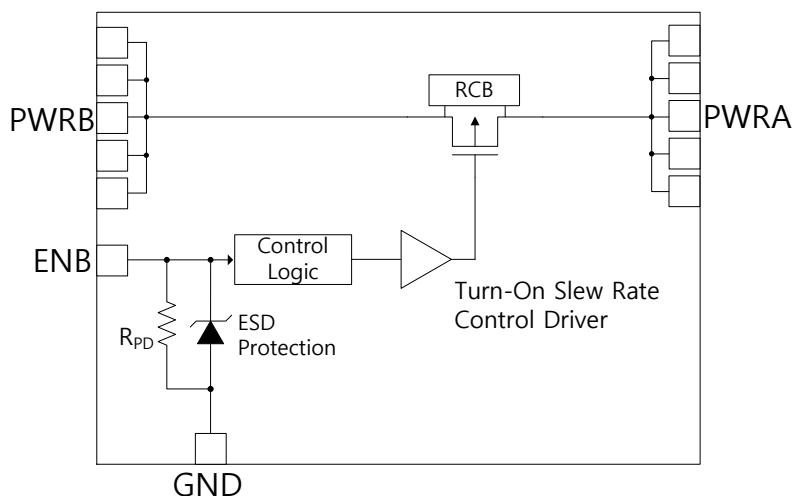
Top View and Bottom View



Pin Description

| Name | No. | Description |
|------|--------------------|--|
| PWRA | A2, B2, B4, C2, C4 | Power Input / Output : Bi-directional power path |
| PWRB | A1, A3, B1, B3, C3 | Power Input / Output : Bi-directional power path |
| GND | C1 | Ground |
| ENB | A4 | ON/OFF control, Active Low |

Functional Block Diagram





Absolute Maximum Ratings ^(Note 1)

| Symbol | Parameter | Min | Max | Unit |
|-----------|--|------|------|------------------|
| V_{VIN} | PWRA, PWRB, ENB to GND | -0.3 | 6.0 | V |
| I_{SW} | Maximum Continuous Switch Current | | 6.0 | A |
| P_D | Power Dissipation at $T_A = 25^\circ\text{C}$ (Derate 7.22 mW/ $^\circ\text{C}$ above 25 $^\circ\text{C}$) | | 902 | mW |
| T_{STG} | Storage Junction Temperature | -65 | +150 | $^\circ\text{C}$ |
| T_A | Operating Temperature Range | -40 | +85 | $^\circ\text{C}$ |
| ESD | HBM on All Pins (Note 2) | 8.0 | | kV |
| | CDM on All Pins (Note 3) | 2.0 | | |

Note 1: Stresses beyond the above listed maximum ratings may damage the device permanently. Operating above the recommended conditions for extended time may stress the device and affect device reliability. Also the device may not operate normally above the recommended operating conditions. These are stress ratings only.

Note 2: ESD tested per JESD22-A114C.

Note 3: ESD tested per JESD22-C101E

Recommended Operating Conditions ^(Note 1)

| Symbol | Parameter | Min | Max | Unit |
|----------------------|---|-----|-----|------------------|
| PWRA, PWRB | Supply Input (or Output) Voltage | 2.3 | 5.5 | V |
| ENB | Enable Logic High Voltage | 1.6 | 5.5 | V |
| | Enable Logic Low Voltage | 0 | 0.4 | V |
| C_{PWRA}, C_{PWRB} | Input / Output Capacitor | | 0.1 | uF |
| T_A | Ambient Temperature ^(Note 2) | -40 | 85 | $^\circ\text{C}$ |

Note 1: Normal Operation of the device is not guaranteed if operating the device over outside range of recommended conditions.

Note 2: The ambient temperature may have to be de-rated if used in high power dissipation and poor thermal resistance conditions.

Package Thermal Resistance

| Parameter | Value | Unit |
|--|-------|--------------------|
| θ_{JA} , 1.235 mm X 1.625 mm WLCSP-12Ball | 138.6 | $^\circ\text{C/W}$ |



RoHS Compliant
HALOGEN-FREE

Confidential

Datasheet Version 1.0

Electrical Characteristics

Min & Max Limits apply for $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ and for $2.3\text{V} \leq V_{IN} \leq 5.5\text{V}$ (Unless otherwise noted).
Typical values are at $V_{IN} = 4.2\text{V}$ and $T_A = 25^{\circ}\text{C}$ (Unless otherwise noted). (Note 1)

| Parameter | Test Condition | | Min | Typ. | Max | Unit |
|--------------------------|-------------------------------------|--|-----|------|------|------|
| SUPPLY OPERATION | | | | | | |
| V_{PWRA} V_{PWRB} | Input voltage range | | 2.3 | | 5.5 | V |
| I_{PWRA} I_{PWRB} | Quiescent Current | $V_{EN/} = \text{Low}, T_A=25^{\circ}\text{C}$ | | | 1 | uA |
| I_{SHDN} | Shutdown Current | $V_{EN/} = 5.5\text{V}, (V_{PWRA} = 5.5\text{V}, V_{PWRB} = \text{open}) \text{ or } (V_{PWRB} = 5.5\text{V}, V_{PWRA} = \text{open}), T_A=25^{\circ}\text{C}$ | | | 1 | uA |
| INTERNAL FET | | | | | | |
| R_{ON} | On-Resistance Between PWRA and PWRB | $T_A = +25^{\circ}\text{C}, I_{LOAD} = 100\text{mA}, V_{PWRA/B} = 2.3\text{V}$ | | 10.0 | 16.0 | mΩ |
| | | $T_A = +25^{\circ}\text{C}, I_{LOAD} = 100\text{mA}, V_{PWRA/B} = 3.3\text{V}$ | | 7.0 | 10.0 | |
| ENABLE INPUT | | | | | | |
| V_{IH} | Enable Input Logic-High Voltage | | 1.6 | | | V |
| V_{IL} | Enable Input Logic-Low Voltage | | | | 0.4 | V |
| R_{PD} | Enable Internal Pull down Resistor | | | 500 | 700 | kΩ |
| DYNAMIC | | | | | | |
| t_{ON} | Turn-On Time | $V_{IN}=4.2\text{V}, R_L=100\Omega, C_L=0.1\mu\text{F}, T_A=25^{\circ}\text{C}$ | | 3 | | ms |
| t_{OFF} | Turn-Off Time | $V_{IN}=4.2\text{V}, R_L=100\Omega, C_L=0.1\mu\text{F}, T_A=25^{\circ}\text{C}$ | | 3 | | ms |

Note 1: All devices under mass production are tested at $T_c=+25^{\circ}\text{C}$. Specifications over the operating temperature range are not guaranteed.



Typical Operating Characteristics

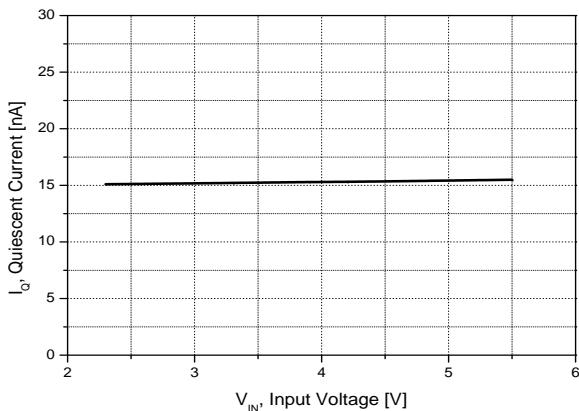


Figure 1. Quiescent Current vs. Input Voltage

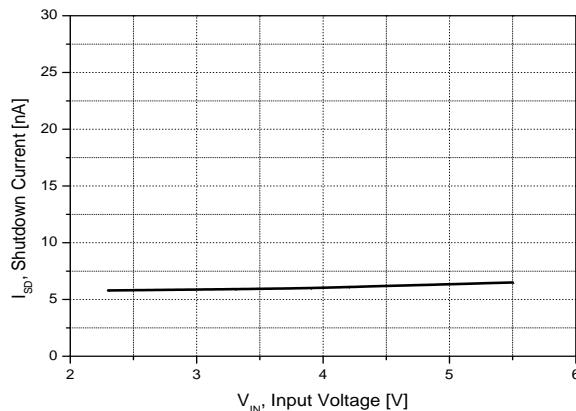


Figure 2. Shutdown Current vs. Input Voltage

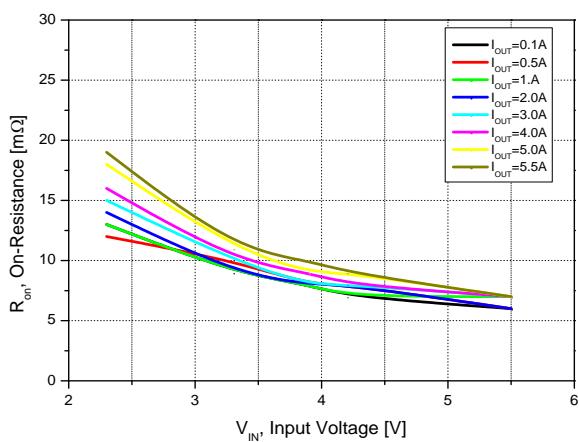


Figure 3. On-Resistance vs. Input Voltage

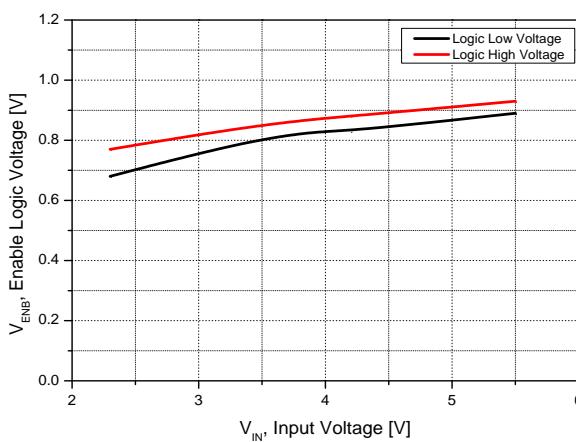


Figure 4. Enable Logic Voltage vs. Input Voltage

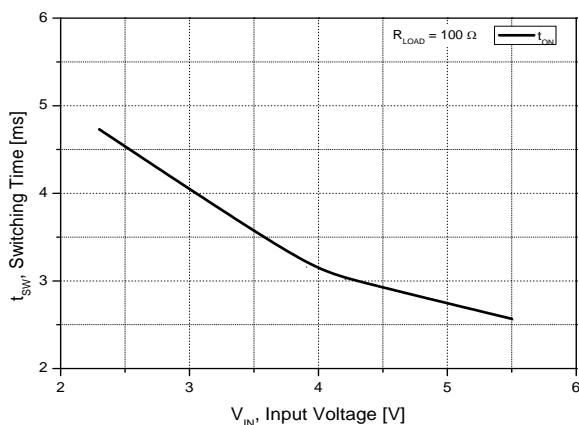


Figure 5. Turn-On Time vs. Input Voltage

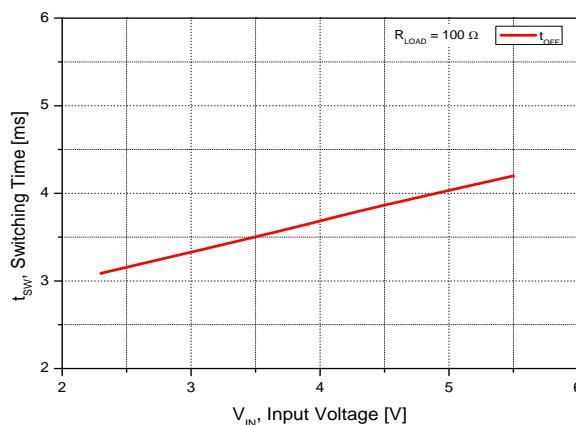


Figure 6. Turn-Off Time vs. Input Voltage



Typical Operating Characteristics

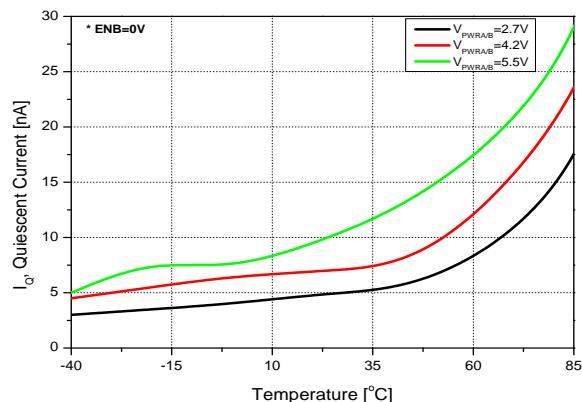


Figure 7. Quiescent Current vs. Temperature

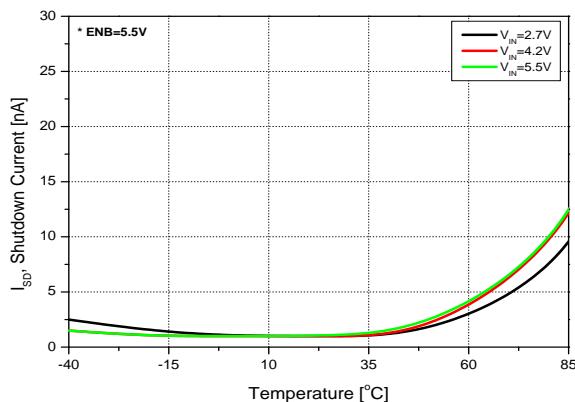


Figure 8. Shutdown Current vs. Temperature

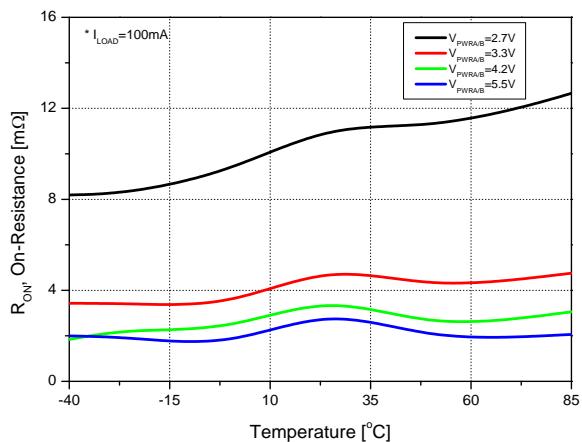


Figure 9. On-Resistance vs. Temperature

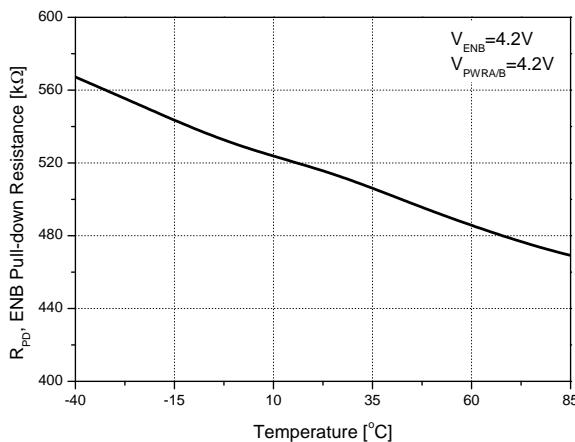


Figure 10. ENB Pull-down Resistance vs. Temperature

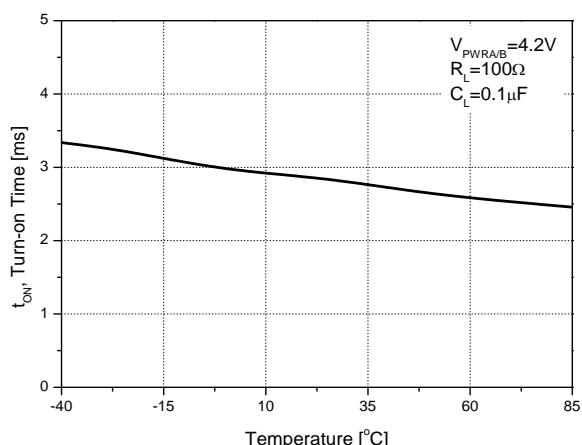


Figure 11. Turn-On Time vs. Temperature

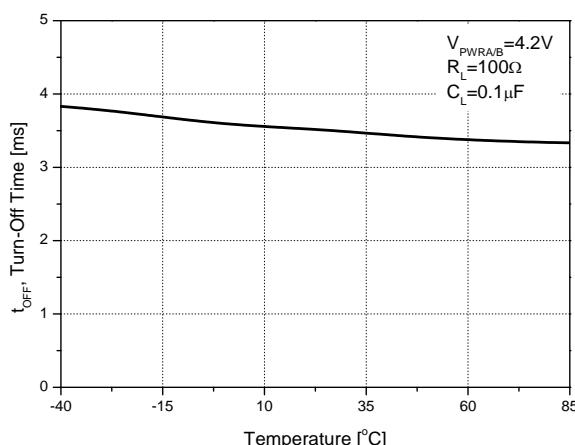


Figure 12. Turn-Off Time vs. Temperature



Overview

The MSI2006 is a low Ron P-channel MOSFET controlled by a soft-start sequence of 2ms for Mobile applications.

Bi-directional switching allows reverse current from V_{OUT} to V_{IN} . The switching is controlled by active-LOW logic input the ENB pin.

The input voltage range operates from 2.3V to 5.5VDC to support a wide range of applications in consumer, optical, storage, portable and industrial device power management.

The device is packaged 1.235mm x 1.625mm, Wafer-Level Chip-Scale Package (WLCSP).

Reverse Current Blocking

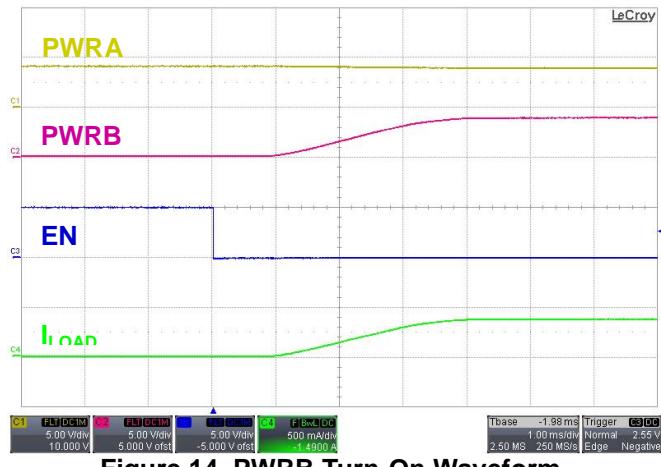
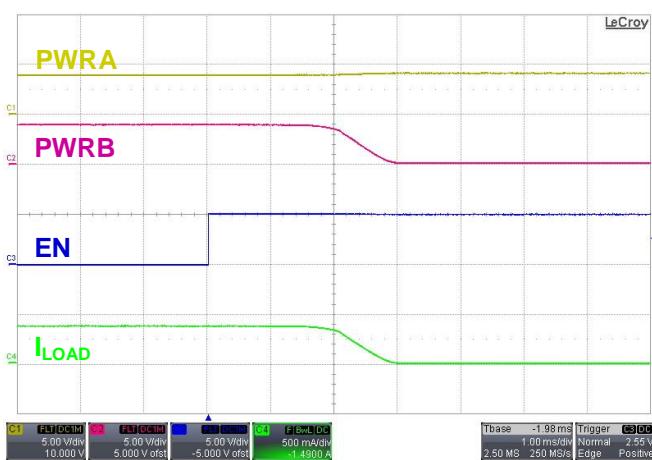
The MSI2006 bi-directional switch prevents current flowing from either port to the other when device is disabled.

ENB Input

The MSI 2006's switch position is controlled by an ENB active low logic input. The switch is on when ENB is logic low and off when ENB is logic high. ENB is internally pulled down to ground by R_{PD} .

Switch On and Off Performance

The MSI2006 has slew rate control. This minimizes the inrush current and provides a soft turn on.
($C_{PWRA/B}=0.1\mu F$, $V_{PWRA}=4.2V$, $R_{LOAD}=10\Omega$)





RoHS Compliant
HALOGEN-FREE

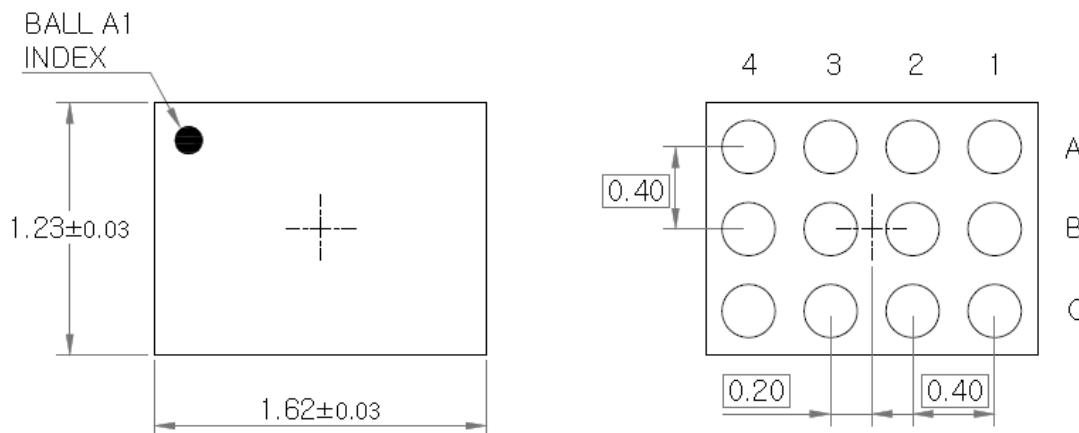
Confidential

Datasheet Version 1.0

MSI2006 – 6A Bi-directional Load Switch for Tablet

Physical Dimensions

1.235 mm X 1.625 mm WLCSP-12Ball



TOP VIEW

BOTTOM VIEW

SIDE VIEW

MagnaChip Semiconductor Ltd. does not recommend the use of its products in hostile environments, including, without limitation, aircraft, nuclear power generation, medical appliances, and devices or systems in which malfunction of any product can reasonably be expected to result in a personal injury. Seller's customers using or selling Seller's products for use in such applications do so at their own risk and agree to fully defend and indemnify Seller.

MagnaChip reserves the right to change the specifications and circuitry without notice at any time. MagnaChip does not consider responsibility for use of any circuitry other than circuitry entirely included in a MagnaChip product.

MagnaChip® is a registered trademark of MagnaChip Semiconductor Ltd.

MagnaChip Semiconductor Ltd.

891, Daechi-Dong, Kangnam-Gu, Seoul, 135-738 Korea

Tel : 82-2-6903-3451 / Fax : 82-2-6903-3668 ~9

www.magnachip.com